

KOH and TMAH Etching Hazard Assessment - HA

Equipment	Wet Deck 2C
Process Area	KOH and TMAH Si Etch Process
Location	Wet Aisle 2C, Cleanroom (W1-062 ECERF)
Assessed By	Scott Munro
Date of Assessment	01 Mar 2024
Final Assessment	HIGH



Please Review

Carefully review and familiarize yourself with the hazard assessment applicable to your tool or process.